# **BASIC BLADE & BEAM SOCKET**

(0.50 mm) .0197" PITCH • BSH SERIES



# **BSH** Mates:

### **SPECIFICATIONS**

Insulator Material: Black LCP Contact Material: Phosphor Bronze Plating: Au or Sn over 50 µ" (1.27 µm) Ni Current Rating: 2 A per pin (2 pins powered) Operating Temp Range: -55 °C to +125 °C Voltage Rating: 175 VAC Max Cycles:

## **PROCESSING**

# Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (030-090) (0.15 mm) .006" max (120-150)\* \*(.004" stencil solution may be available; contact ipg@samtec.com)
Board Stacking:

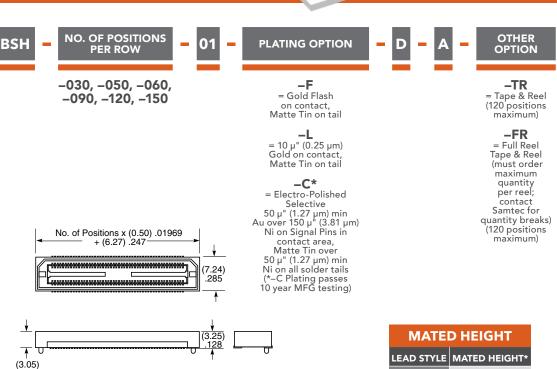
For applications requiring more than two connectors per board or 90 positions or higher, contact ipg@samtec.com

# ALSO AVAILABLE MOQ Required

 $30 \, \mu$ " (0.76  $\mu$ m) Gold **Edge Mount Capability** 8 mm, 11 mm, 16 mm, 19 mm and 22 mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.) (11 mm, 16 mm, 19 mm and 22 mm not available with 50 positions)



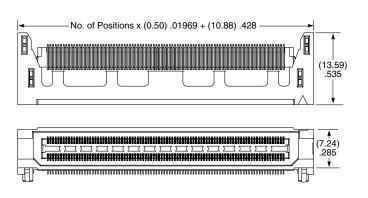
Some lengths, styles and options are non-standard, non-returnable.

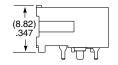


## **NO. OF POSITIONS BSH PER ROW** -030, -060, -090

= Gold Flash on contact, Matte Tin on tail

= 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail





(5.00 mm) .1971"

OPTION

-GP

= Guide

Post

\*Processing conditions will affect mated height.